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Dual 1-of-4 FET Multiplexer / Demultiplexer



ADE-205-616A (Z)

Rev.1 May 2001

Description

The HD74CBT3253 is a dual 1-of-4 high-speed TTL-compatible FET multiplexer / demultiplexer. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

1OE, 2OE, S0, and S1 select the appropriate B output for the A-input data.

Features

- Minimal propagation delay through the switch.
- 5 Ω switch connection between two ports.
- TTL-compatible input levels.
- Ultra low quiescent power.
 - -Ideally suited for notebook applications.

Function Table

Inputs

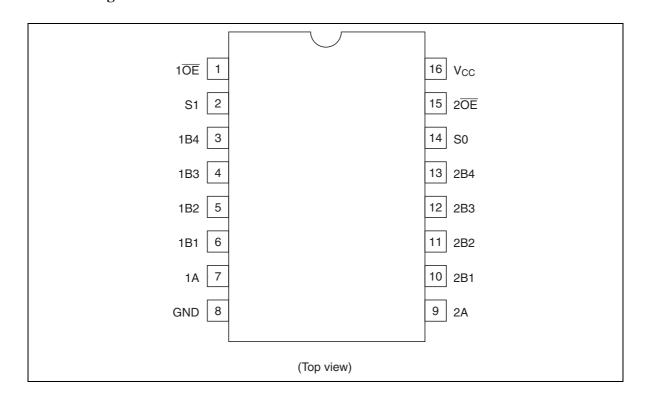
1 <mark>OE</mark>	2 OE	S1	S0	Function
X	Н	X	Х	Disconnect 1A and 2A
Н	Х	Х	Х	Disconnect 1A and 2A
L	L	L	L	1A to 1B1 and 2A to 2B1
L	L	L	Н	1A to 1B2 and 2A to 2B2
L	L	Н	L	1A to 1B3 and 2A to 2B3
L	L	Н	Н	1A to 1B4 and 2A to 2B4

H: High level L: Low level

X:

Pin Arrangement

Immaterial



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit	Conditions
Supply voltage range	V _{cc}	-0.5 to 7.0	V	
Input voltage range 1	V _i	-0.5 to 7.0	V	
Input clamp current	I _{IK}	-50	mA	V ₁ < 0
Continuous output current	I _o	128	mA	$V_o = 0$ to V_{cc}
Continuous current through V _{cc} or GND	I _{CC} or I _{GND}	±100	mA	
Maximum power dissipation at Ta = 25°C (in still air) ^{'2}	$P_{\scriptscriptstyle T}$	500	mW	TSSOP
Storage temperature	Tstg	-65 to 150	°C	

Notes:

The absolute maximum ratings are values which must not individually be exceeded, and furthermore, no two of which may be realized at the same time.

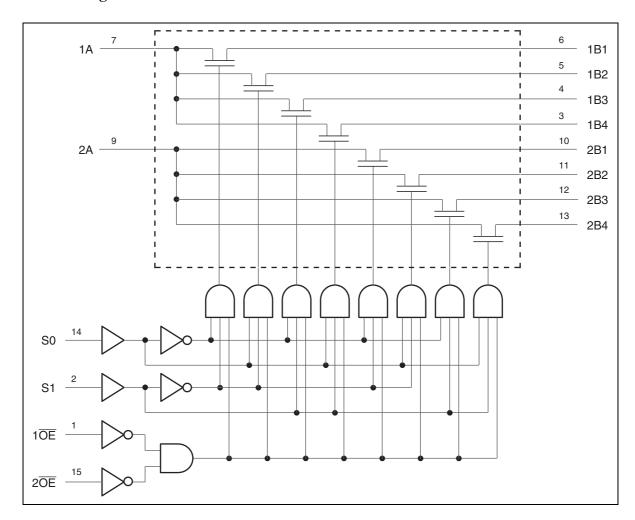
- 1. The input and output voltage ratings may be exceeded even if the input and output clamp-current ratings are observed.
- 2. The maximum package power dissipation was calculated using a junction temperature of 150°C.

Recommended Operating Conditions

Item	Symbol	Min	Max	Unit	Conditions
Supply voltage range	V _{cc}	4.0	5.5	V	
Input voltage range	V _I	0	5.5	V	
Output voltage range	V _{I/O}	0	5.5	V	
Input transition rise or fall rate	Δt / Δν	0	5	ns / V	$V_{cc} = 4.5 \text{ to } 5.5 \text{ V}$
Operating free-air temperature	Та	-40	85	°C	_

Note: Unused or floating inputs must be held high or low.

Block Diagram



DC Electrical Characteristics

 $(Ta = -40 \text{ to } 85^{\circ}C)$

Item	Symbol	$V_{cc}(V)$	Min	Typ⁻¹	Max	Unit	Test conditions		
Clamp diode voltage	V _{IK}	4.5	_	_	-1.2	V	$I_{IN} = -18 \text{ mA}$		
Input voltage	V _{IH}	4.0 to 5.5	2.0	_	_	V			
	V _{IL}	4.0 to 5.5	_	_	0.8				
On-state switch resistance *2	R _{on}	4.5	_	5	7	Ω	$V_{IN} = 0 \text{ V},$ $I_{IN} = 64 \text{ mA}$		
		4.5	_	5	7		$V_{IN} = 0 \text{ V},$ $I_{IN} = 30 \text{ mA}$		
		4.5	_	10	15		$V_{IN} = 2.4 \text{ V},$ $I_{IN} = 15 \text{ mA}$		
Input current	I _{IN}	0 to 5.5	_	_	±1.0	μΑ	V _{IN} = 5.5 V or GND		
Off-state leakage current	l _{oz}	5.5	_	_	±1.0	μΑ	0 ≤ A, B ≤ V _{cc}		
Quiescent supply current	I _{cc}	5.5	_	_	3	μΑ	$V_{IN} = V_{CC}$ or GND, $I_{O} = 0$ mA		
Increase in I _{cc} per input ^{'3}	ΔI_{cc}	5.5	_	_	2.5	mA	One input at 3.4 V, other inputs at $V_{\rm cc}$ or GND		

Notes: For condition shown as Min or Max use the appropriate values under recommended operating conditions.

- 1. All typical values are at V_{cc} = 5 V (unless otherwise noted), Ta = 25°C.
- 2. Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower voltage of the two (A or B) terminals.
- 3. This is the increase in supply current for each input that is at the specified TTL voltage level rather than $V_{\rm cc}$ or GND.

Capacitance

 $(Ta = 25^{\circ}C)$

Item		Symbol	V _{cc} (V)	Min	Тур	Max	Unit	Test conditions
Control input capacitance		C _{IN}	5.0	_	3.5	_	pF	$V_{IN} = 0 \text{ or } 3 \text{ V}$
Input / output	A port	C _{I/O (OFF)}	5.0	_	15	_	pF	V _o = 0 or 3 V
capacitance	B port	_	5.0		5	_		$\overline{OE} = V_{cc}$

Note: This parameter is determined by device characterization is not production tested.

Switching Characteristics

 $(Ta = -40 \text{ to } 85^{\circ}C)$

•
$$V_{CC} = 4.0 \text{ V}$$

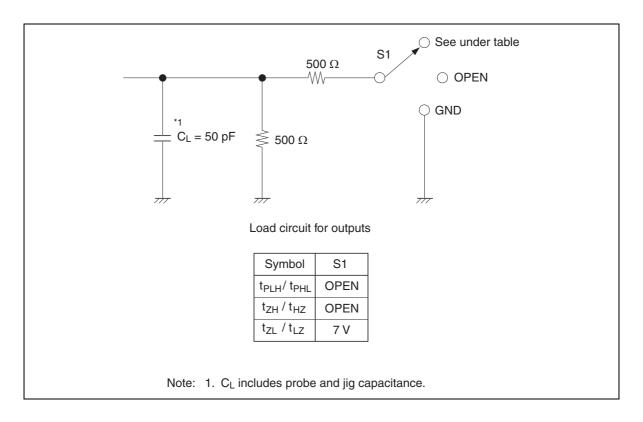
Item	Symbol	Min	Max	Unit	Test conditions	FROM (Input)	TO (Output)
Propagation delay time *1	t _{PLH} t _{PHL}	_	0.35	ns	$C_L = 50 \text{ pF}$ $R_L = 500 \Omega$	A or B	B or A
Propagation delay time	t _{PLH} t _{PHL}	_	6.6	ns	$C_L = 50 \text{ pF}$ $R_L = 500 \Omega$	S	A
Enable time	t _{zh} t _{zL}	_	7.1	ns	$C_L = 50 \text{ pF}$ $R_L = 500 \Omega$	S	В
		_	7.3			ŌE	A or B
Disable time	t _{HZ} t _{LZ}	_	7.9	ns	$C_L = 50 \text{ pF}$ $R_L = 500 \Omega$	S	В
		_	7.3			ŌĒ	A or B

•
$$V_{cc} = 5.0 \pm 0.5 \text{ V}$$

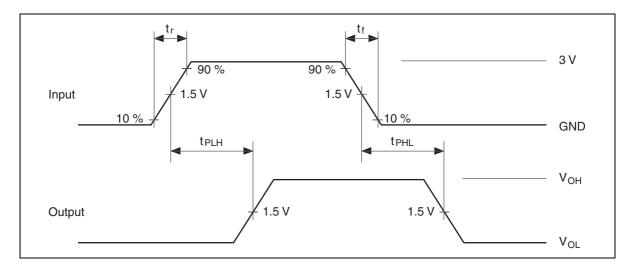
Item	Symbol	Min	Max	Unit	Test conditions	FROM (Input)	TO (Output)
Propagation delay time '1	t _{PLH} t _{PHL}	_	0.25	ns	$C_L = 50 \text{ pF}$ $R_L = 500 \Omega$	A or B	B or A
Propagation delay time	t _{PLH} t _{PHL}	1.6	6.2	ns	$C_L = 50 \text{ pF}$ $R_L = 500 \Omega$	S	A
Enable time	t _{zh} t _{zL}	1.3	6.3	ns	$C_L = 50 \text{ pF}$ $R_L = 500 \Omega$	S	В
		1.4	6.4			ŌĒ	A or B
Disable time	t _{HZ} t _{LZ}	1.1	7.4	ns	$C_L = 50 \text{ pF}$ $R_L = 500 \Omega$	S	В
		2.3	7.0			ŌĒ	A or B

Note: 1. The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

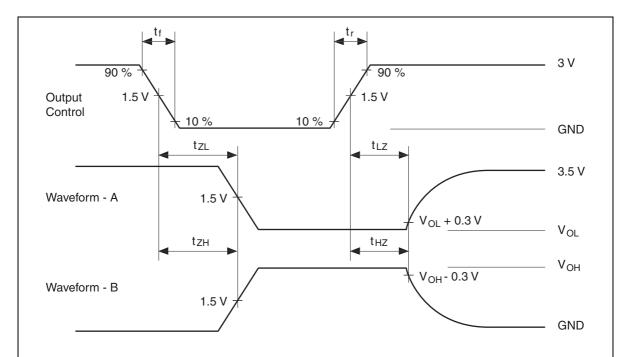
Test Circuit



Waveforms - 1



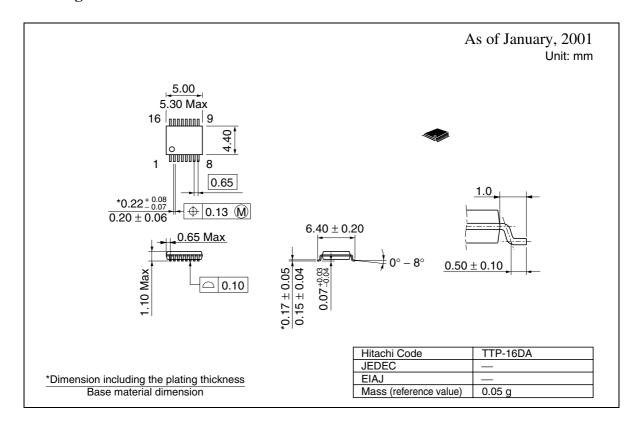
Waveforms - 2



Notes: 1. All input pulses are supplied by generators having the following characteristics : PRR \leq 10 MHz, $Z_O = 50~\Omega$, $t_r \leq 2.5~ns$, $t_f \leq 2.5~ns$.

- 2. Waveform A is for an output with internal conditions such that the output is low except when disabled by the output control.
- 3. Waveform B is for an output with internal conditions such that the output is high except when disabled by the output control.
- 4. The output are measured one at a time with one transition per measurement.

Package Dimensions



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